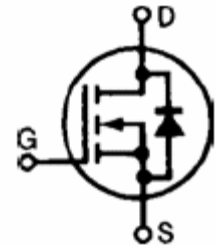
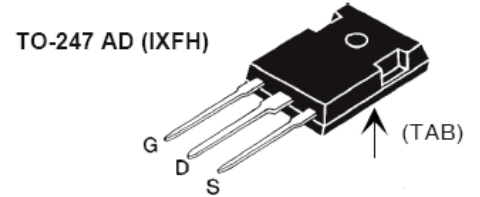


N-Channel Enhancement Mode Switch Mode RF MOSFET  
Low Capacitance Z-MOS™ MOSFET Process  
Optimized for RF Operation  
Ideal for Class C, D, & E Applications

$V_{DSS} = 1200 \text{ V}$   
 $I_{D25} = 8.0 \text{ A}$   
 $R_{DS(on)} = 2.1 \Omega$   
 $P_{DC} = 300 \text{ W}$

Symbol	Test Conditions	Maximum Ratings	
$V_{DSS}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$	1200	V
$V_{DGR}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$ ; $R_{GS} = 1 \text{ M}\Omega$	1200	V
$V_{GS}$	Continuous	$\pm 20$	V
$V_{GSM}$	Transient	$\pm 30$	V
$I_{D25}$	$T_c = 25^\circ\text{C}$	8	A
$I_{DM}$	$T_c = 25^\circ\text{C}$ , pulse width limited by $T_{JM}$	40	A
$I_{AR}$	$T_c = 25^\circ\text{C}$	8	A
$E_{AR}$	$T_c = 25^\circ\text{C}$	TBD	mJ
$dv/dt$	$I_S \leq I_{DM}$ , $di/dt \leq 100 \text{ A}/\mu\text{s}$ , $V_{DD} \leq V_{DSS}$ , $T_J \leq 150^\circ\text{C}$ , $R_G = 0.2 \Omega$	5	V/ns
	$I_S = 0$	>200	V/ns
$P_{DC}$		300	W
$P_{DAMB}$	$T_c = 25^\circ\text{C}$	3.0	W
$R_{thJC}$		0.5	$^\circ\text{C}/\text{W}$



		min.	typ.	max.	
$V_{DSS}$	$V_{GS} = 0 \text{ V}$ , $I_D = 4 \text{ ma}$	1200			V
$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$	3.5		6.5	V
$I_{GSS}$	$V_{GS} = \pm 20 \text{ V}_{DC}$ , $V_{DS} = 0$			$\pm 100$	nA
$I_{DSS}$	$V_{DS} = 0.8 V_{DSS}$ $V_{GS} = 0$	$T_J = 25^\circ\text{C}$		50	$\mu\text{A}$
		$T_J = 125^\circ\text{C}$		1	mA
$R_{DS(on)}$	$V_{GS} = 20 \text{ V}$ , $I_D = 0.5 I_{D25}$ Pulse test, $t \leq 300 \mu\text{s}$ , duty cycle $d \leq 2\%$		2.1		$\Omega$
$g_{fs}$	$V_{DS} = 50 \text{ V}$ , $I_D = 0.5 I_{D25}$ , pulse test		10.1		S
$T_J$		-55		+175	$^\circ\text{C}$
$T_{JM}$			175		$^\circ\text{C}$
$T_{stg}$		-55		+ 175	$^\circ\text{C}$
$T_L$	1.6mm(0.063 in) from case for 10 s		300		$^\circ\text{C}$
<b>Weight</b>			3.5		g

#### Features

- IXYS advanced Z-MOS process
- Low gate charge and capacitances
  - easier to drive
  - faster switching
- Low  $R_{DS(on)}$
- Very low insertion inductance (<2nH)

#### Advantages

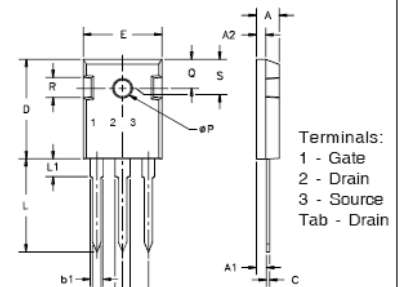
- High Performance RF Z-MOS™
- Optimized for RF and high speed

**PRELIMINARY**

Symbol	Test Conditions	Characteristic Values		
		(T <sub>J</sub> = 25°C unless otherwise specified)		
		min.	typ.	max.
R <sub>G</sub>				1 Ω
C <sub>iss</sub>			1960	pF
C <sub>oss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 0.8 V <sub>DSS(max)</sub> , f = 1 MHz		59	pF
C <sub>rss</sub>			9.2	pF
T <sub>d(on)</sub>			4	ns
T <sub>on</sub>	V <sub>GS</sub> = 15 V, V <sub>DS</sub> = 0.8 V <sub>DSS</sub> I <sub>D</sub> = 0.5 I <sub>DM</sub>		5	ns
T <sub>d(off)</sub>	R <sub>G</sub> < 1 Ω (External)		4	ns
T <sub>off</sub>			6	ns

Source-Drain Diode		Characteristic Values		
		(T <sub>J</sub> = 25°C unless otherwise specified)		
Symbol	Test Conditions	min.	typ.	max.
I <sub>S</sub>	V <sub>GS</sub> = 0 V			8 A
I <sub>SM</sub>	Repetitive; pulse width limited by T <sub>JM</sub>			48 A
V <sub>SD</sub>	I <sub>F</sub> =I <sub>S</sub> , V <sub>GS</sub> =0 V, Pulse test, t ≤ 300μs, duty cycle ≤2%			1.5 V
T <sub>rr</sub>			TBD	ns

TO-247 AD (IXFH) Outline



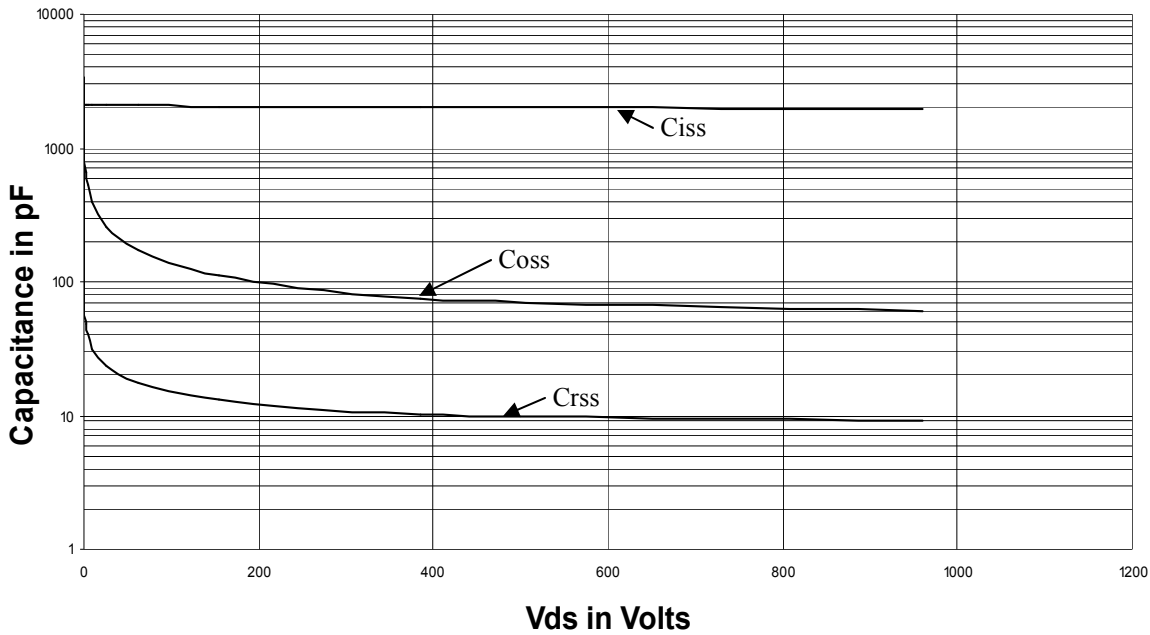
Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.7	5.3	.185	.209
A <sub>1</sub>	2.2	2.54	.087	.102
A <sub>2</sub>	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b <sub>1</sub>	1.65	2.13	.065	.084
b <sub>2</sub>	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L1		4.50		.177
ØP	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15	BSC	.242	BSC

IXYS RF reserves the right to change limits, test conditions and dimensions.

IXYS RF MOSFETS are covered by one or more of the following U.S. patents:

4,835,592    4,860,072    4,881,106    4,891,686    4,931,844    5,017,508  
 5,034,796    5,049,961    5,063,307    5,187,117    5,237,481    5,486,715  
 5,381,025    5,640,045    6,404,065    6,583,505    6,710,463    6,727,585  
 6,731,002

**PRELIMINARY**



**IXZ308N120 Capacitances verses Vds**

**PRELIMINARY**